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Part Number: 0738001000

Status: Active

Overview: HDM Backplane Connector System

Description: HDM Board-to-Board Midplane Header, Vertical, SMC, Press-Fit, Long Pin, Open End

Option, 144 Circuits

Documents:

3D ModelPackaging Specification PK-70873-0868 (PDF)3D Model (PDF)Test Summary TS-73670-990-001 (PDF)Drawing (PDF)RoHS Certificate of Compliance (PDF)

Product Specification PS-73780-999-001 (PDF)

Agency Certification

CSA LR19980 UL E29179

General

Product Family Backplane Connectors

Series <u>73800</u>
Application Midplane
Component Type PCB Header

Overview HDM Backplane Connector System

Product Name HDM

UPC 800755946376

Physical

Circuits (Loaded) 144
Circuits (maximum) 144

Color - Resin Black, Natural

Durability (mating cycles max)

First Mate / Last Break

Flammability

Guide to Mating Part

Keying to Mating Part

Mone

Material - Plating Mating

Material - Plating Termination

A Sold

Material - Plating Termination

Material - Resin High Temperature Thermoplastic

Yes

Net Weight 8.289/g Number of Columns 24

Number of Pairs Open Pin Field

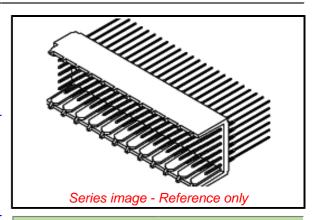
Number of Rows 6
Orientation Vertical

PC Tail Length 11.50mm PCB Locator No **PCB** Retention Yes PCB Thickness - Recommended 4.00mm Packaging Type Tube Pitch - Mating Interface 2.00mm Pitch - Termination Interface 2.00mm Plating min - Mating 0.762µm Plating min - Termination 0.051um Polarized to PCB No Stackable Yes

Temperature Range - Operating -55° to +105°C

Electrical

Surface Mount Compatible (SMC)



EU ELV

Not Relevant

EU RoHS China RoHS

Compliant REACH SVHC Not Contained Per -ED/71/2019 (16 July

2019)

Halogen-Free

Status

Low-Halogen

For more information, please visit Contact US

China ROHS Green Image
ELV Not Relevant
RoHS Phthalates Not Contained

Search Parts in this Series

73800 Series

Mates With

73632 HDM+ Board-to-Board Daughtercard Receptacle. 73780 HDM Board-to-Board

Daughtercard Receptacle

Application Tooling | FAQ

Tooling specifications and manuals are found by selecting the products below. Crimp Height Specifications are then contained in the Application Tooling Specification document.

Global

Description Product # Backplane Insertion 622005703

Head for 144 Circuits

Current - Maximum per Contact
Data Rate
1.0 Gbps
Real Signals (per 25mm)
75
Shielded
No
Voltage - Maximum
250V AC

Solder Process Data

Lead-freeProcess Capability N/A

Material Info

Reference - Drawing Numbers

Packaging Specification PK-70873-0868
Product Specification PS-73780-999-001
Sales Drawing SD-73800-001
Test Summary TS-73670-990-001

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